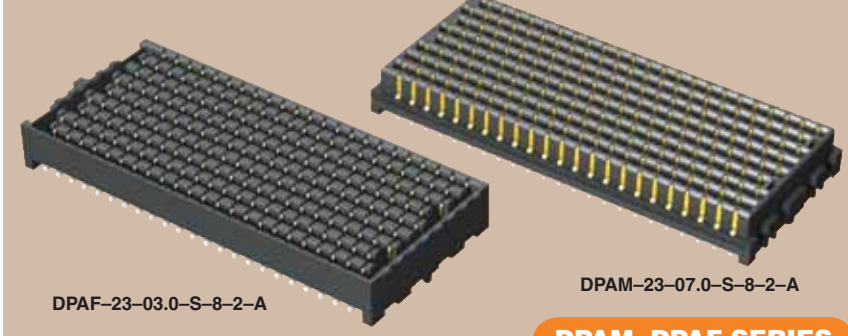
samtec

DP ARRAY®

(2,16 mm) .085"



DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:
DPAF

DPAF Mates with:
DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au over 50µ" (1,27 µm) Ni
Current Rating (2x3):
2.9 A per pin
Operating Temp Range:
-55°C to +125°C
Contact Resistance:
10.4mΩ
Working Voltage:
300 VAC
Mated Cycles: 100 Cycles
RoHS Compliant: Yes
Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

Protocols Supported

Fibre Channel
Rapid I/O
PCI Express®
SATA
InfiniBand™
XAUI
MGT (Rocket I/O)

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

ALSO AVAILABLE
(MOQ Required)

- Tin-Lead Solder Charge
- Other platings

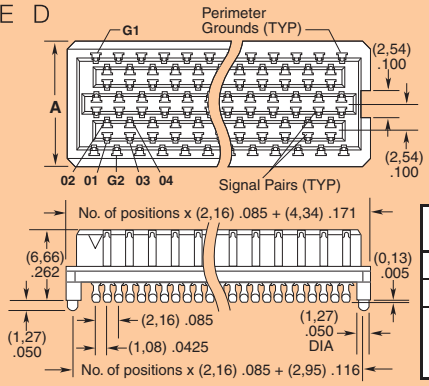
Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

DPAM	–	PAIRS PER ROW	–	07.0	–	PLATING OPTION	–	NO. OF ROWS	–	SOLDER TYPE	–	A	–	OPTION
		–04, –06, –08, –15, –23				–S =30µ" (0,76 µm) Gold on contact area, Tin on solder tail		–8 =Eight Pair Rows; –3 =Three Pair Rows		–2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp				–K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad; –TR =Tape & Reel; –GP =Guide Post (–23 only)

Final Inch® CERTIFIED

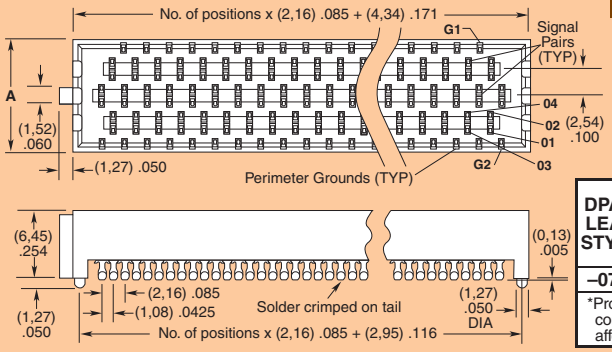


NO OF ROWS	A
–8	(24,59) .968
–3	(11,89) .468

DPAM/DPAF 10 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	7 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?DPAM, www.samtec.com?DPAF or contact sig@samtec.com

DPAF	–	PAIRS PER ROW	–	03.0	–	PLATING OPTION	–	NO. OF ROWS	–	SOLDER TYPE	–	A	–	OPTION
		–04, –06, –08, –15, –23				–S =30µ" (0,76 µm) Gold on contact area, Tin on solder tail		–8 =Eight Pair Rows; –3 =Three Pair Rows		–2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp				–K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad; –TR =Tape & Reel



NO OF ROWS	A
–8	(23,32) .918
–3	(10,62) .418

DPAM LEAD STYLE	DPAF MATED HEIGHT* –03.0
–07.0	10 mm

*Processing conditions will affect mated height.

SIZE	USABLE PAIRS PER ARRAY*
–04 x –3	6 Pairs
–06 x –3	12 Pairs
–04 x –8	16 Pairs
–06 x –8	32 Pairs
–08 x –8	48 Pairs
–15 x –8	104 Pairs
–23 x –8	168 Pairs
–08 x –3	18 Pairs
–15 x –3	39 Pairs
–23 x –3	63 Pairs

*Assumes first and last pair in each row are grounded